ABSTRACT OF THE DISCLOSURE

An intermediate base supports a semiconductor module on a printed circuit board. The intermediate base has an upper face on which the semiconductor component is directly mounted with its component connecting elements facing the upper face. The base has through-holes which are incorporated from a lower face of the base body so that the component conducting elements of the semiconductor component are exposed. The through-holes are then at least partially coated with a metal layer, which also contacts the exposed portions of the component connecting elements. Each of the through-holes has at least a partially annular notch, so that each through-hole extends through a recessed stud, which is used to form an external connection for the module onto the printed circuit board.